

Layout And Use Of Bond Pads And Probe Pads For Testing Of
Integrated Circuits Devices
Atty. Dkt. No. : M-9433 US Inventor: XXXXXXXXXX Brian E. Ong
Sheet 1 of 9

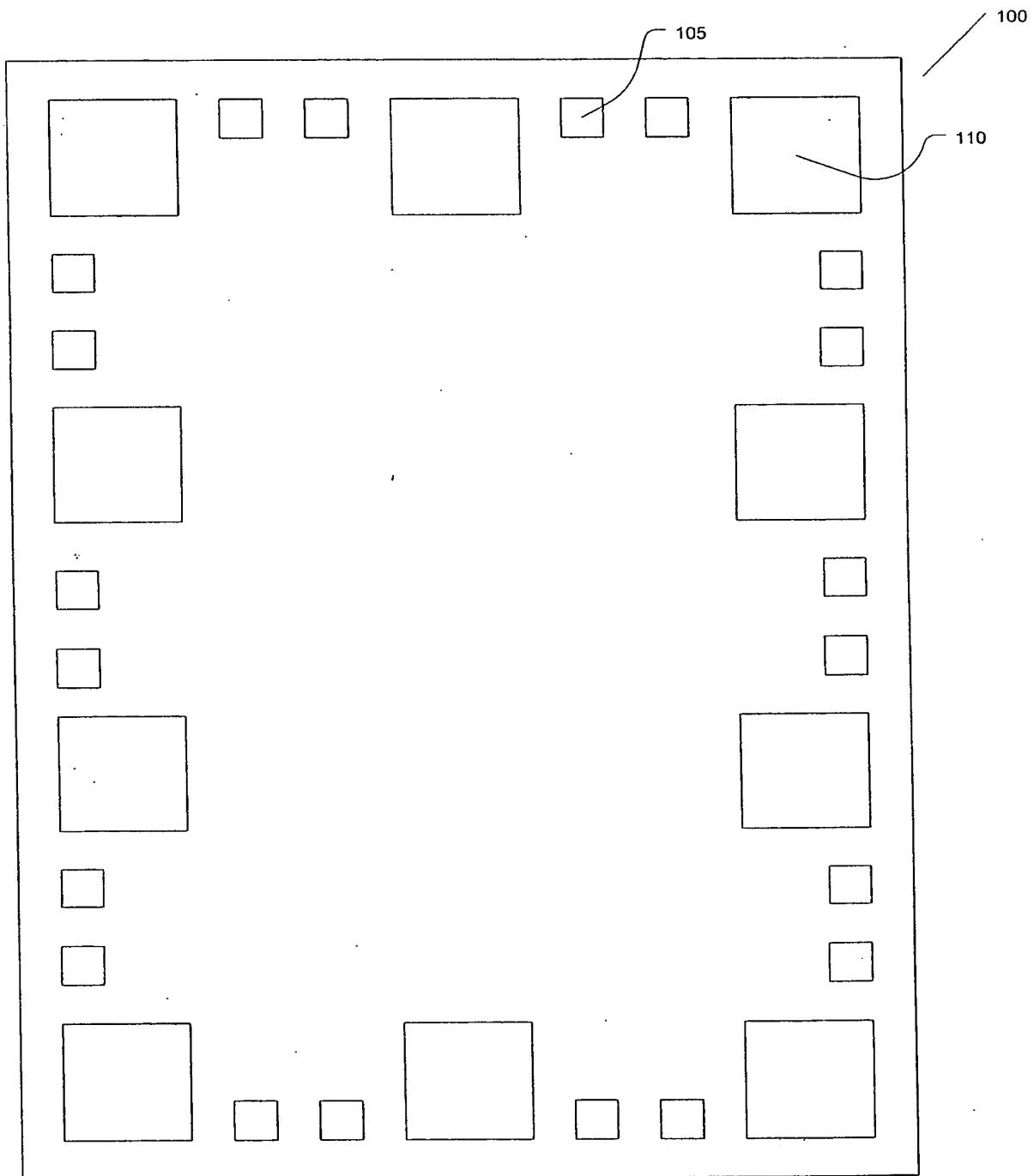


FIG. 1

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Integrated Circuits Devices
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Sheet 2 of 9

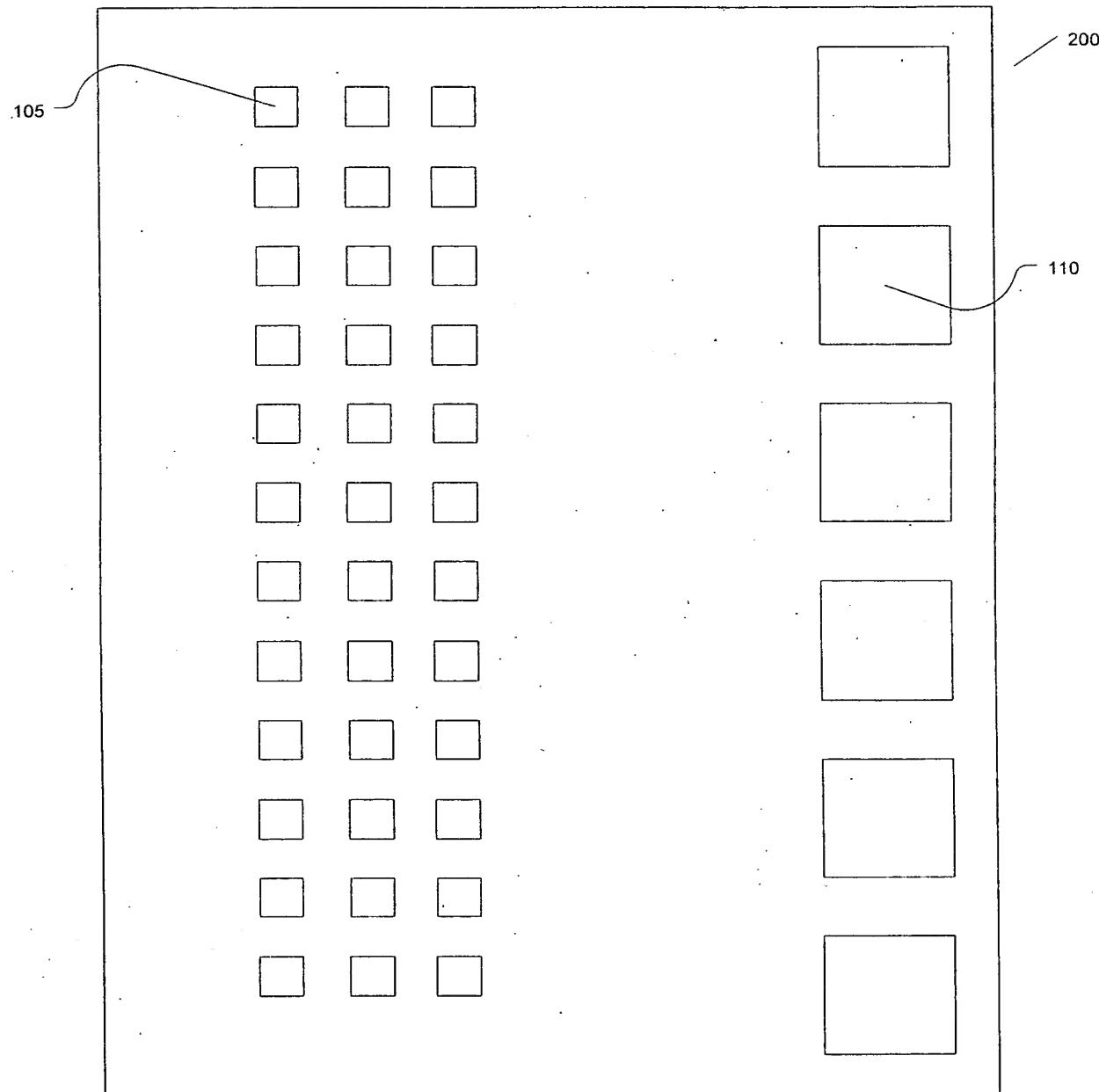


FIG. 2

Layout And Use Of Bond Pads And Probe Pads For Testing Of
Integrated Circuits Devices
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Sheet 3 of 9

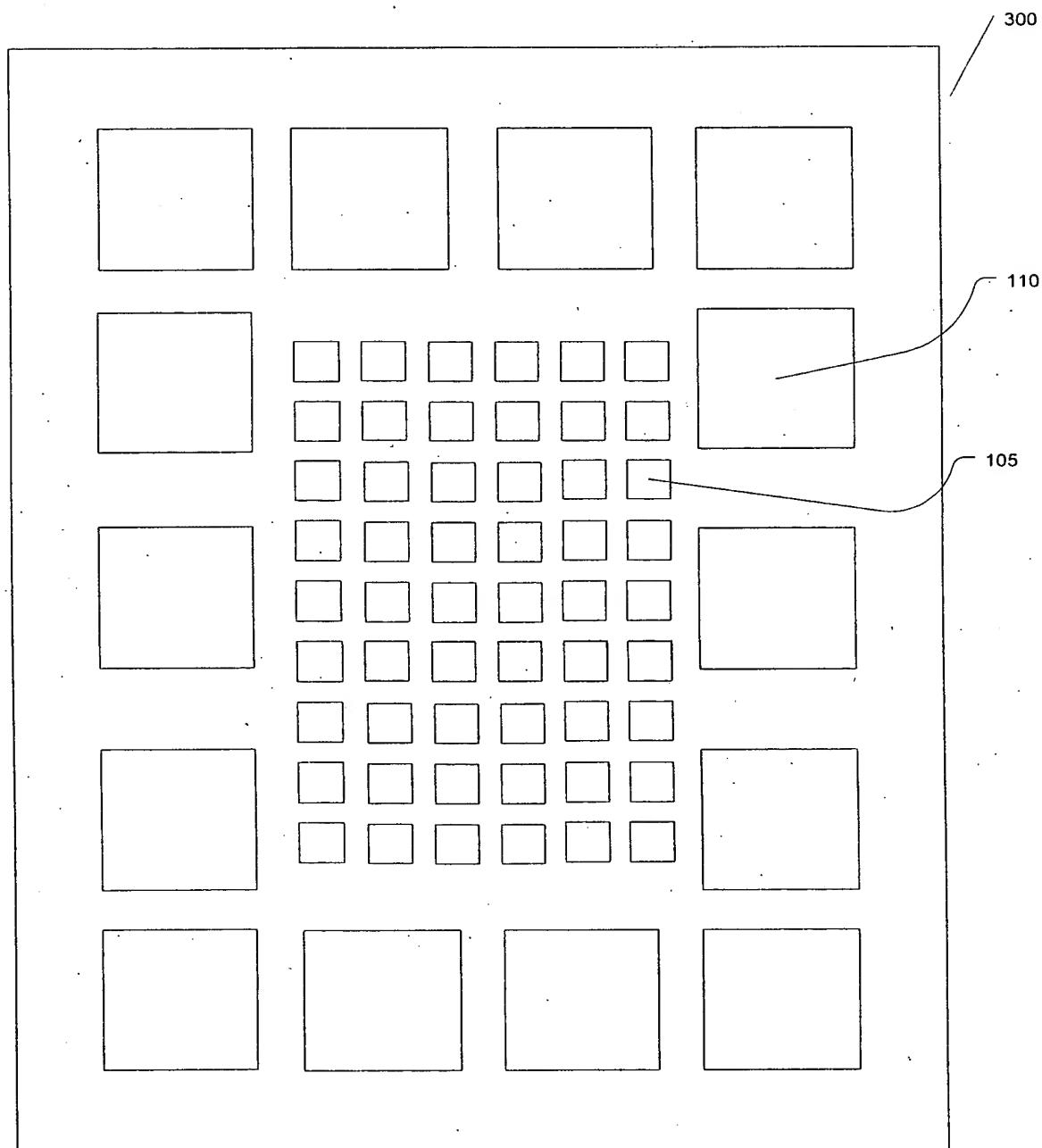


FIG. 3

140a
140b
130a
130b
105a
105b
110
120
400

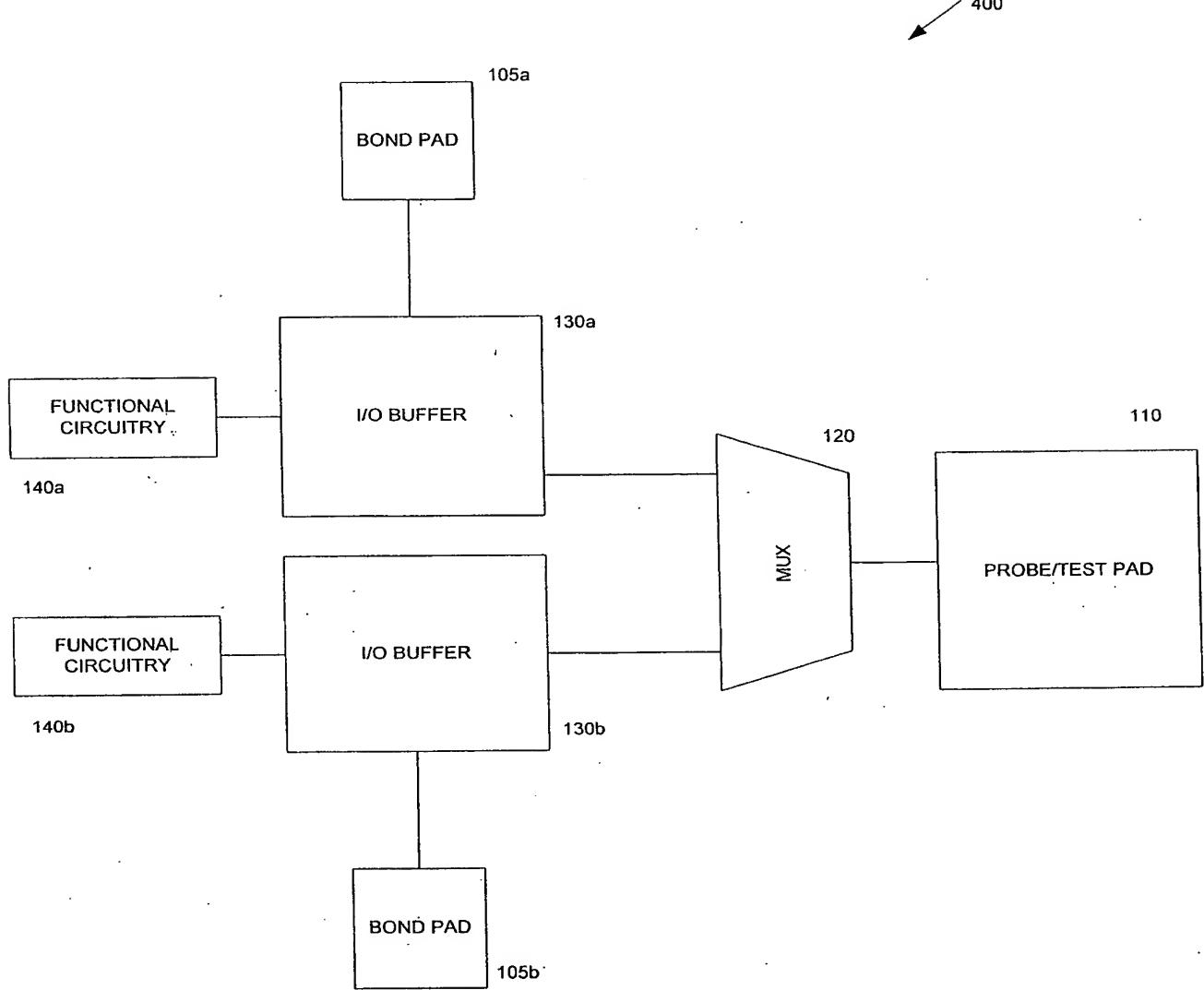


FIG. 4

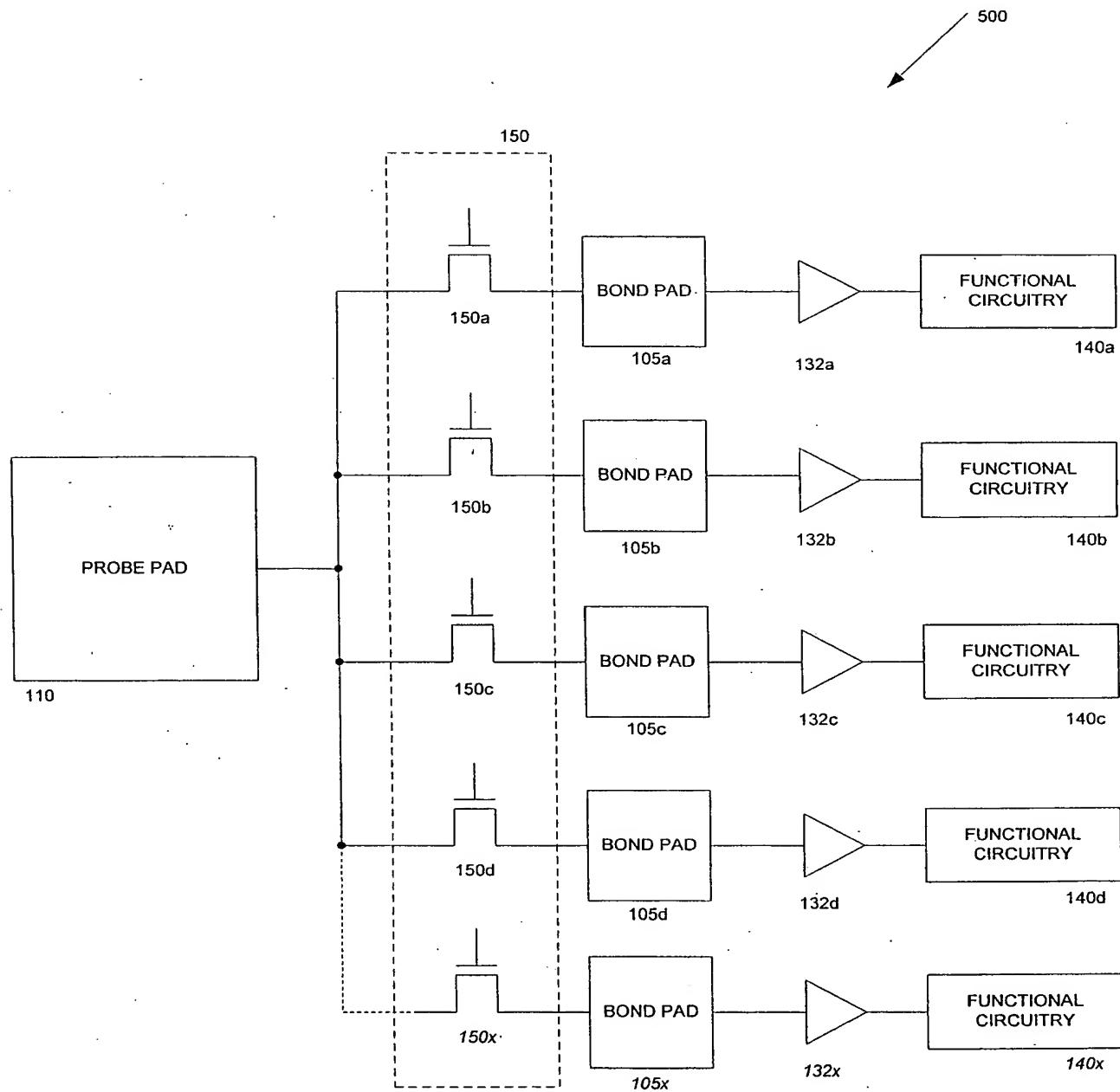


FIG. 5

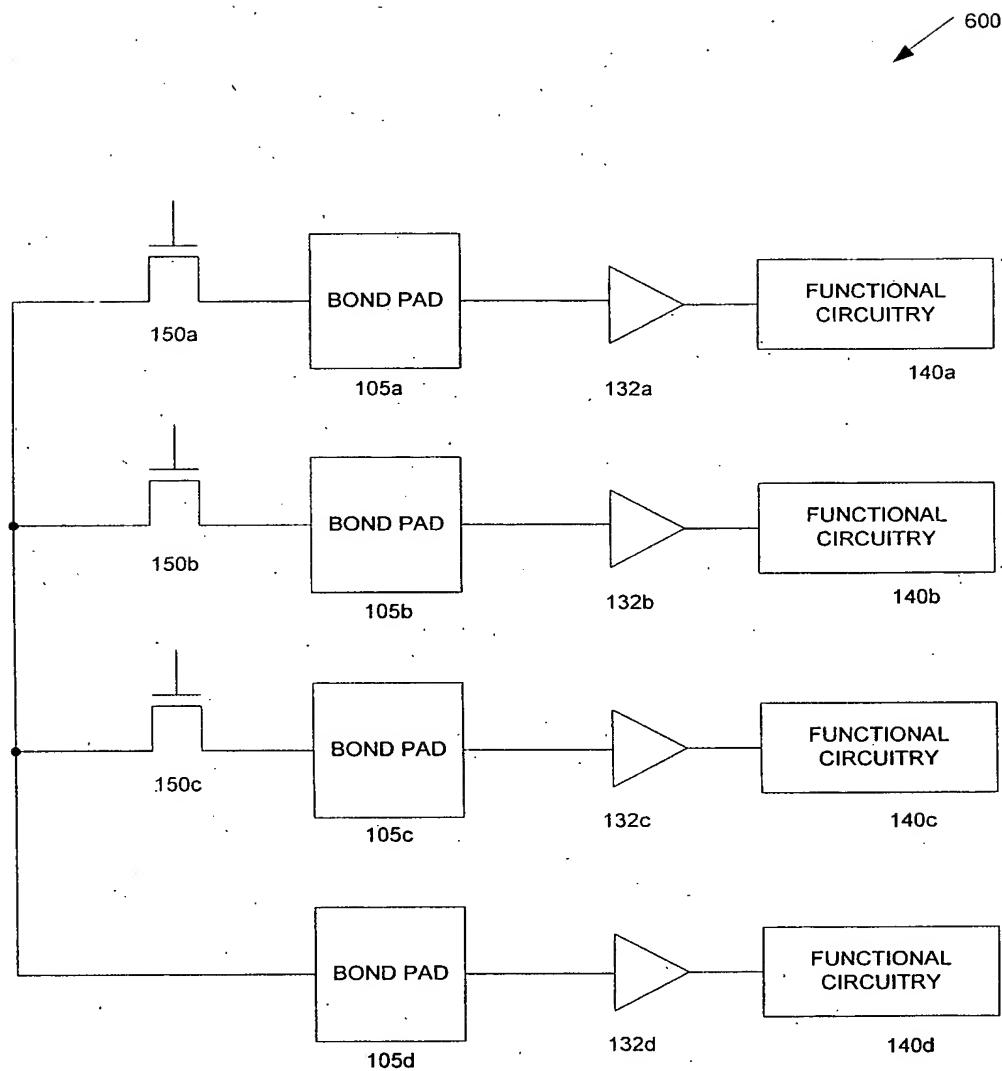


FIG. 6

Layout And Use Of Bond Pads And Probe Pads For Testing Of
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A Dkt. No. : M-9433 US Inventor: Adri Ong
Sheet 7 of 9

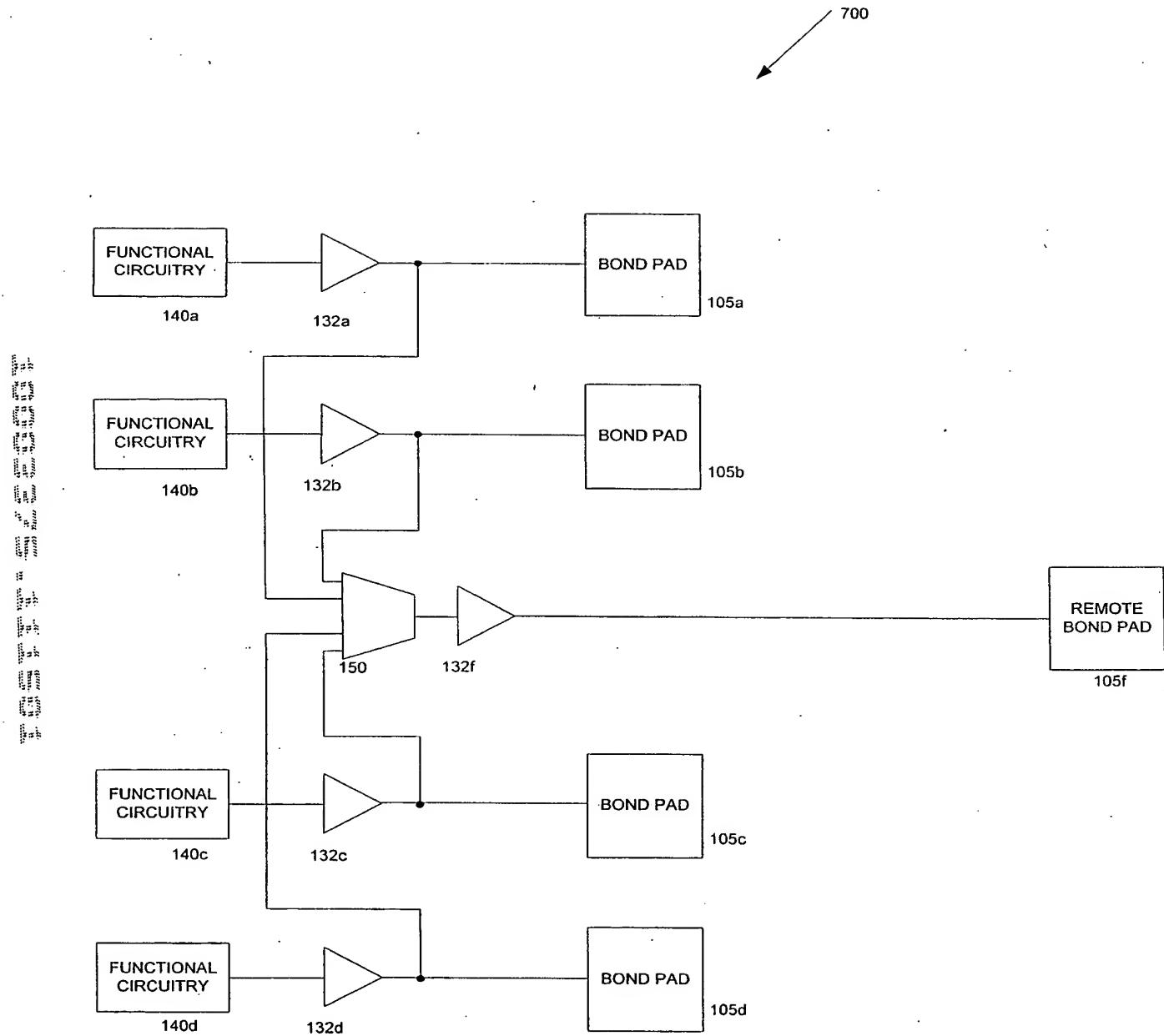


FIG. 7

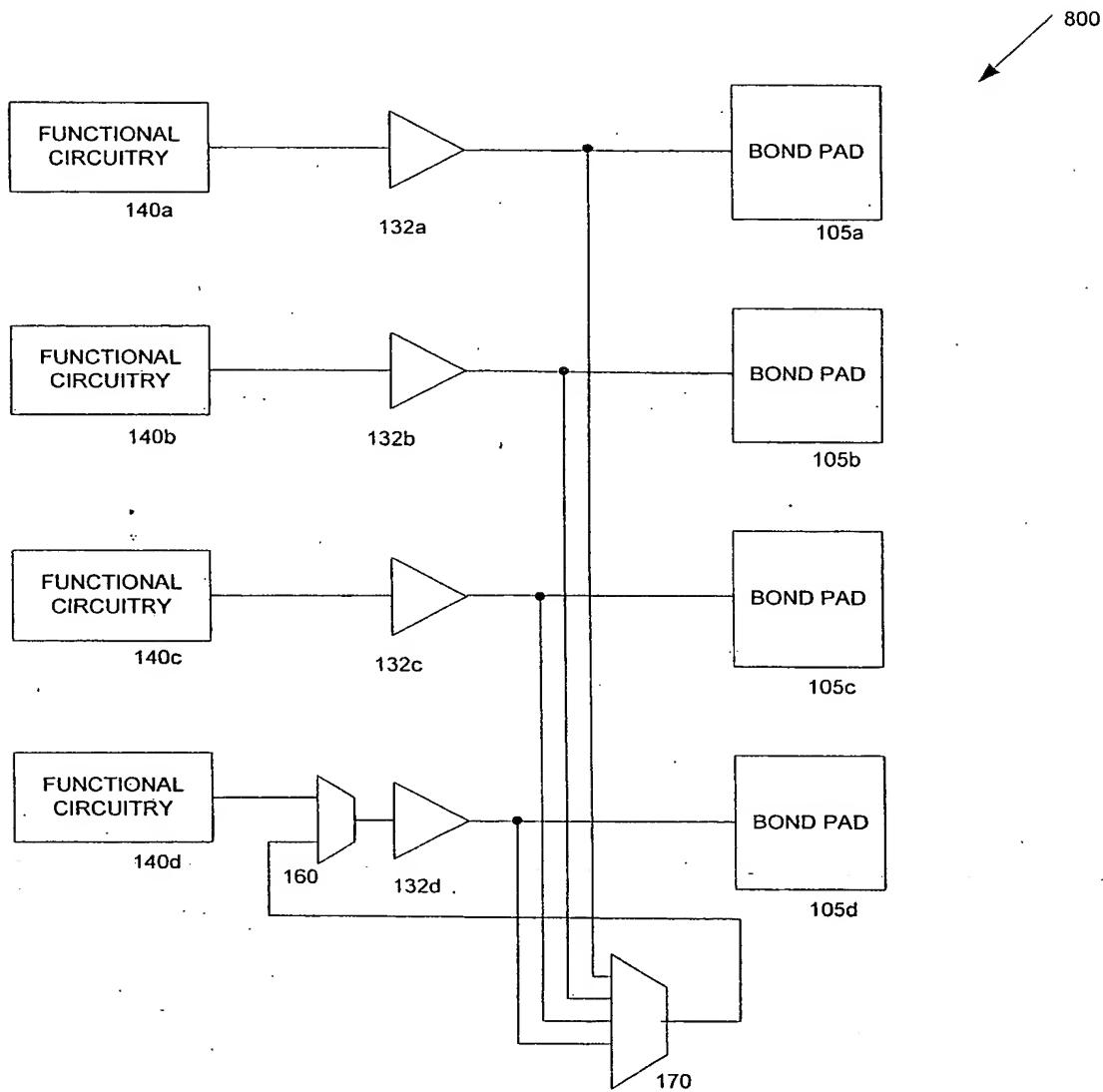


FIG. 8

Layout And Use Of Bond Pads And Probe Pads For Testing Of
Integrated Circuits Devices
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Sheet 9 of 9

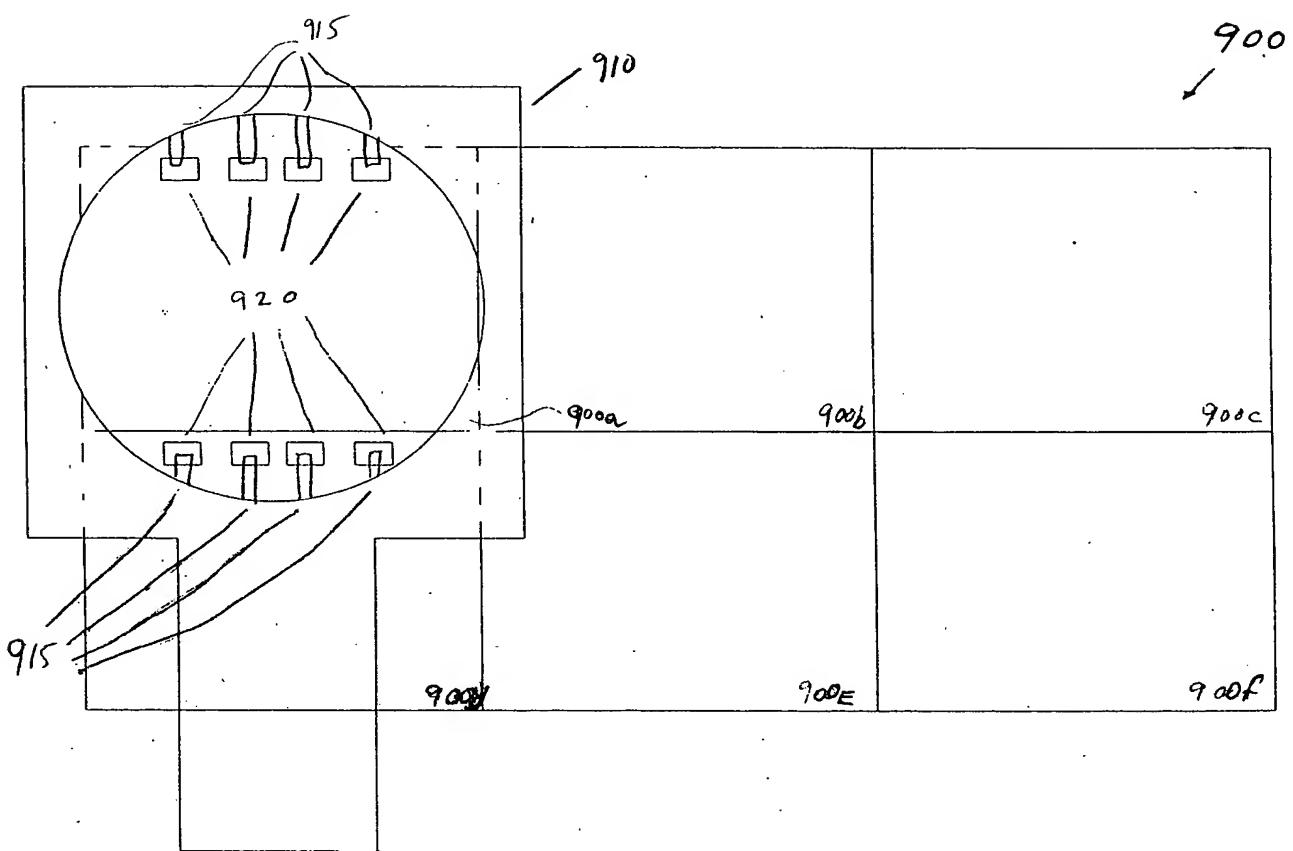


FIG. 9